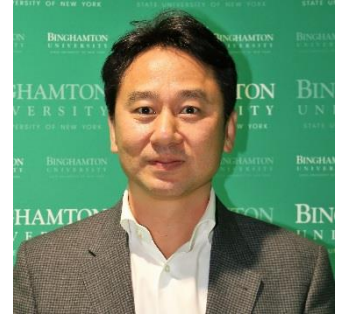




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Prof. Seungbae (SB) Park is a Distinguished Professor of Mechanical engineering of the State University of New York (SUNY) at Binghamton. He is also the director of Integrated Electronics Engineering Center (IEEC), a New York State Center for Advanced Technology (CAT). He received his Ph.D. from Purdue University in 1994 and received his MS and BS degree from Seoul National University. He worked for IBM Microelectronics before joining SUNY Binghamton.

He has more than 200 technical publications and holds 4 US patents. Dr. Park was elected as an IEEE Fellow, ASME Fellow, Chair of IEEE Electronic Packaging Society Thermal/Mechanical Technical Committee, Chair of ASME Electronics and Photonics Packaging Division, Former Chair of ASME K-16 Committee on Heat Transfer in Electronic Equipment, and served as an associate editor for ASME Journal of Electronic Packaging.